



NTC THERMISTORS: TYPE HM

LEADLESS CHIP THERMISTOR

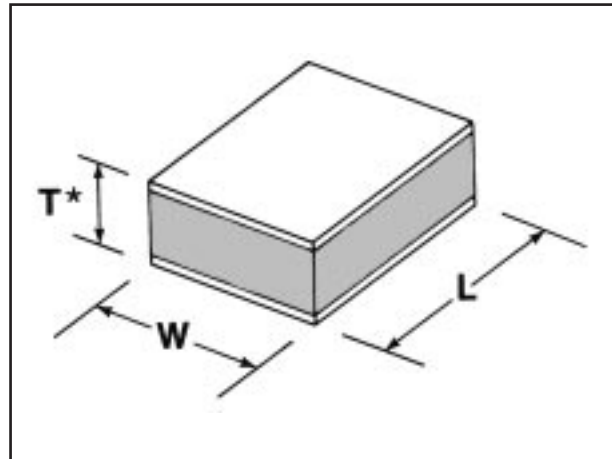
DESCRIPTION:

Top and bottom electroded, uncoated chip thermistors without leads.

FEATURES:

- Low cost, solid state temperature sensor
- Point matched at 25°C to ±5% to ±10%
- Suitable for use over range of -80°C to +150°C
- High sensitivity greater than -4%/°C at 25°C
- Suitable for temperature measurement, control and compensation
- Palladium Silver contacts suitable for soldering or conductive epoxy bonding
- Sizes from .025" x .025" to .085" x .085" available
- Most popular R-vs-T curves are available
- Not suitable for immersion in fluids or high humidity

DIMENSIONS:



Select appropriate part number below for resistance and temperature tolerance desired

R _{25°C}	MATERIAL SYSTEM	WIDTH "W" (inches)	LENGTH "L" (inches)	THICK. "T" (inches)	R _{25°C} ± 5%	R _{25°C} ± 10%
2252	F	.070	.070	.010	HM70NF232J	HM70NF232K
2252	F	.085	.085	.015	HM85NF232J	HM85NF232K
3000	F	.060	.060	.010	HM60NF302J	HM60NF302K
3000	F	.075	.075	.015	HM75NF302J	HM75NF302K
5000	F	.050	.050	.010	HM50NF502J	HM50NF502K
5000	F	.060	.060	.015	HM60NF502J	HM60NF502K
10000	F	.035	.035	.010	HM35NF103J	HM35NF103K
10000	F	.040	.045	.015	HM40NF103J	HM40NF103K
10000	Y	.045	.045	.010	HM45NY103J	HM45NY103K
10000	Y	.055	.055	.015	HM55NY103J	HM55NY103K
30000	H	.025	.025	.010	HM25NH303J	HM25NH303K
30000	H	.030	.035	.015	HM30NH303J	HM30NH303K
100000	Y	.030	.030	.010	HM30NY104J	HM30NY104K
100000	Y	.035	.035	.015	HM35NY104J	HM35NY104K

OPTIONS:

Consult factory for availability of options:

- Other resistance values in the range of 100Ω - 100kΩ
- Other tolerances
- Other reference temperature
- Gold electrodes suitable for wire bonding
- Other sizes

DATA:

- **THERMAL AND ELECTRICAL PROPERTIES:**
- **Dissipation constant:**(still air) 7-15 mW/K
- **Thermal time constant:** (still air) 10-45 sec.
- The thermal time constant and dissipation constant values are dependent upon the method of mounting. The above values represent the range of smallest to largest HM thermistor chips when soldering to an aluminum substrate .025" thick using 2% silver solder.